



Click [here](#) for the 3D model.

Dimensions

Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
T	1.4mm +/-0.15mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	4700 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms